

#### NOTES:

1. PCB SHALL BE FABRICATED TO IPC-6011 AND 6012 CLASS 2 OR BETTER
2. MATERIAL AS DEFINED IN STACK-UP
3. FINISHED THICKNESS: 0.055 +/- 0.007"
4. FINISH: ENIG
5. SOLDER MASK: BLUE LPI PER IPC-SM-840-C, CLASS T
6. SOLDER MASK CLEARANCE PADS IN GERBER DATA ARE THE SAME SIZE AS COPPER PADS. VENDOR MAY CREATE CLEARANCES TO FIT YOUR PROCESSES UP TO 0.003" CLEARANCE. SIDES: TOP LAYER (ONLY)
7. SOLDER MASK COVERS PADS IN GERBER DATA ON BOTTOM SIDE. VENDOR MAY ADJUST TO AVOID MASK IN VIAS, BOTTOM SIDE.
8. SILKSCREEN: NON-CONDUCTIVE WHITE EPOXY BASED INK; NOT ALLOWED ON COMPONENT PADS OR IN MOUNTING HOLES.
9. HOLE SIZES AFTER PLATING AND FINAL CONDUCTOR FINISH SHALL BE PER DRILL TABLE ON DRILL DRAWING. CENTERLINE OF HOLES SHALL BE WITHIN 0.005" RADIAL OF EXACT CENTERLINE OF THE PAD ON THE ARTWORK.
10. ALL 6 MIL (0.15 mm) VIAS, DESIGNATED "A" IN DRILL DRAWING ARE VIA-IN-PAD AND MUST BE FILLED AND FINISHED.
11. 100% TESTING FOR OPENS AND SHORTS REQUIRED.
12. PERFORM GERBER FILE DATABASE DESIGN RULE CHECK.
13. IMPEDANCE REQUIREMENTS AS SHOWN IN LAYER STACK-UP TABLE. VENDOR MAY ADJUST TRACE SIZE OR LAYER THICKNESS AS NECESSARY TO ACHIEVE THE IMPEDANCE REQUIREMENTS.
14. EMBEDDED RESISTORS ARE 100 OHMS +/-20%
15. VENDOR MAY ALTER PHOTO DATA (GERBER) TO COMPENSATE FOR ETCHING PROCESS
16. VENDOR MAY REMOVE NONFUNCTIONAL PADS AND ADD TEARDROPPING
17. ALL IMPEDANCE COUPONS MUST BE SERIALIZED TO INDICATE WHICH BOARD THEY CORRESPOND TO. ALL IMPEDANCE COUPONS TO BE SUPPLIED WITH BOARDS.
18. SOLDERABILITY TEST, CATEGORY 2 OF J-STD-003 OR STRESSED MICROSECTION



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ENGINEER: Steve Wint

PART:	71-563300	REV	A
DATE:	1/31/2014	SHEET	1 OF 3

PADS / FOIL

N7305

POWER

N7205

GND

N7305

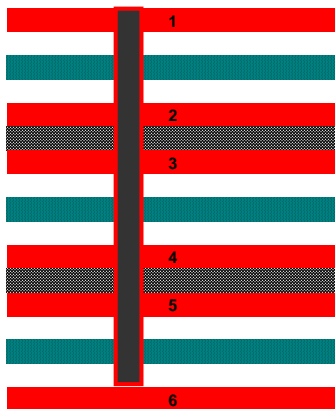
SIGNAL/TICER 50 Ohm/sq

N7205

GND

N7305

PADS / FOIL



0.0019 1/2 OZ CU + plating

0.002 PREPREG

0.00064 1/2 OZ CU

0.003 POLY

0.00064 1/2 OZ CU

0.02 PREPREG

0.00064 Ticer + 1/2 OZ CU, Controlled Impedance

0.02 POLY

0.00064 1/2 OZ CU

0.002 POLY

0.0019 1/2 OZ CU + plating

0.053 Thickness Out Of Lamination



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SHEET 2 OF 3

	Material: POLY
	Finish: Au

	Layer	material	thickness mils	SE +/- 10%			Ticer		
				ohms	mils		ohms		
	Soldermask		0.7						
1	Pads		1.9						
		prepreg	2.0						
2	Plane (PWR)		0.6						
		poly	3.0						
3	Plane (GND)		0.6						
		prepreg	20.0						
4	Signal/Ticer		0.6	100	3.0	Ref 3/5	100		
		poly	20.0						
5	Plane (GND)		0.6						
		prepreg	2.0						
6	Pads		1.9						
	Soldermask		0.7						
	<b>Total:</b>		<b>55</b>						

thickness µm
17.8
48.3
50.8
16.3
76.2
16.3
508.0
16.3
508.0
16.3
50.8
48.3
17.8
<b>1390.9</b>

Tolerance for all Zo targets is +/-10%  
SE = Single Ended

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